

FEATURES AND SPECIFICATIONS

Features and Benefits

- 15A per blade current carrying capacity
- Press-fit on backplane eliminates soldering
- Female on backplane for safety
- 12mm module can be distributed between signal modules as needed
- Metric connector in Futurebus form factor
- Surface Mount Compatible

Reference Information

Product Specification: PS-73651-1998
 Packaging: Tube
 UL File No.: E29179
 Mates With: [73651](#)
 Designed In: Millimeters

Electrical

Current: 15.0A
 Dielectric Withstanding Voltage: 1000V
 Insulation Resistance: 1000 MΩ min.

Mechanical

Insertion Force: 135N max. per press-fit pin
 Retention Force: 22.5N min. per press-fit pin
 Mating Force: 2.5N max. per contact
 Unmating Force: 0.15N min.
 Normal Force: 1.0N min.
 Durability: 250 cycles

Physical

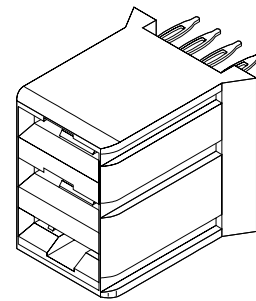
Housing: Liquid crystal polymer
 Contact: 0.4mm Beryllium Copper
 Plating: 30µ" Gold
 Operating Temperature: -55 to +105°C



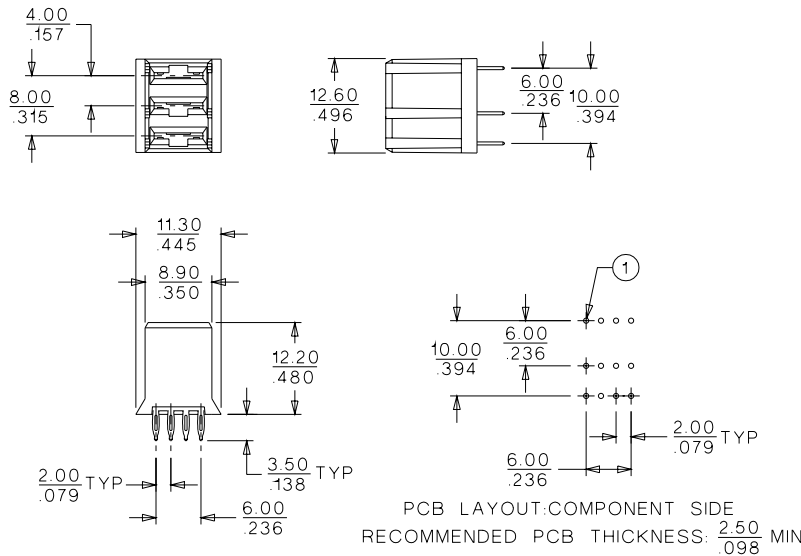
**2.00mm (.079") Pitch
 HDM*
 Board-to-Board
 Backplane Power Module**

73656/73659

**Vertical
 Power Receptacle**



CATALOG DRAWING (FOR REFERENCE ONLY)



- ① $\frac{0.71}{.028}$ DIA plated thru hole TYP
- $\frac{0.838}{0.0330}$ DIA drilled hole

Note: Press-fit version shown

ORDERING INFORMATION

Module	Order No.	Termination	Tail Length
Backplane Power Module	73656-0000	Press-Fit	3.50 (.138)
Midplane Power Module	73659-0001	Solder Tail	2.00 (.079)
Midplane Power Module	73659-0002	Solder Tail	2.50 (.098)
Midplane Power Module	73659-0003	Solder Tail	3.00 (.118)
Midplane Power Module	73659-0004	Solder Tail	3.50 (.138)

* High Density Metric and HDM^{PLUS} are trademarks of Teradyne, Inc.